

as of January 4, 2018

Selection of ceramic microsystems-related papers

M. Schubert, C. Münch, S. Schuurman, V. Poulain, J. Kita, R. Moos:

Characterization of Nickel Manganite NTC thermistor films prepared by Aerosol Deposition at room temperature
Journal of the European Ceramic Society, **38**, 613-619 (2018), doi: 10.1016/j.jeurceramsoc.2017.09.005

M. Schubert, J. Kita, C. Münch, R. Moos:

Analysis of the characteristics of thick-film NTC thermistor devices manufactured by screen-printing and firing technique and by room temperature aerosol deposition method (ADM)
Functional Materials Letters, **10**, 1750073 (2017), doi: 10.1142/S1793604717500734

A. Bogner, C. Steiner, S. Walter, J. Kita, G. Hagen, R. Moos:

Planar Microstrip Ring Resonators for Microwave-Based Gas Sensing: Design Aspects and Initial Transducers for Humidity and Ammonia Sensing
Sensors, **17**, 2422 (2017), doi: 10.3390/s17102422

T. Ritter, G. Hagen, J. Kita, S. Wiegärtner, F. Schubert, R. Moos:

Self-Heated HTCC-based Ceramic Disc for Mixed Potential Sensors and for Direct Conversion Sensors for Automotive Catalysts
Sensors and Actuators B: Chemical, **248**, 793-802 (2017), doi: 10.1016/j.snb.2016.11.079

F. Schubert, M. Gollner, J. Kita, F. Linseis, R. Moos:

Optimization of a sensor for a Tian-Calvet calorimeter with LTCC-based sensor discs
Journal of Sensors and Sensors Systems, **5**, 381-388 (2016), doi: 10.5194/jsss-5-381-2016

F. Schubert, M. Gollner, J. Kita, F. Linseis, R. Moos:

First steps to develop a sensor for a Tian-Calvet calorimeter with increased sensitivity
Journal of Sensors and Sensors Systems, **5**, 205-212 (2016), doi: 10.5194/jsss-5-205-2016

A. Brandenburg, E. Wappler, J. Kita, R. Moos:

Miniaturized ceramic DSC device with strain gauge-based mass detection - First steps to realize a fully integrated DSC/TGA device
Sensors and Actuators A: Physical, **241**, 145-151 (2016), doi: 10.1016/j.sna.2016.02.011

D. Ortolino, J. Kita, K. Beart, R. Wurm, S. Kleinewig, A. Pletsch, R. Moos:

Failure of electrical vias manufactured in thick-film technology when loaded with short high current pulses
Microelectronics Reliability, **56**, 121-128 (2016), doi: 10.1016/j.microrel.2015.10.011

F. Schubert, M. Gollner, J. Kita, F. Linseis, R. Moos:

Optimierung eines neuentwickelten Sensorkopfes für ein Tian-Calvet-Kalorimeter
Sensoren und Messsysteme 2016, 10.5.-11.5.2016, Nürnberg, p. 50-52, doi: 10.5162/sensoren2016/1.2.2

F. Schubert, J. Kita, M. Gollner, F. Linseis, R. Moos:

Sensor Stack for Tian-Calvet Calorimeter made in LTCC-Technology
IMAPS/ACerS 12th International Conference and Exhibition on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT 2016), Denver, April 19-21, 2016, p. 19-23

J. Kita, S. Wiegärtner, A. Prince, P. Weigand, R. Moos:

Evaluation of screen-printable type S (Pt-PtRh) thermocouples on different ceramic substrates
IMAPS/ACerS 12th International Conference and Exhibition on Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT 2016), Denver, April 19-21, 2016, p. 53-57

F. Schubert, M. Gollner, J. Kita, F. Linseis, R. Moos:

Neuentwicklung eines Sensorkopfes für ein Tian-Calvet-Kalorimeter
G. Gerlach, A. Schütze (Hrsg.), *12. Dresdner Sensor-Symposium*, 7.-9. Dezember 2015, Dresden, p. 222-226, doi: 10.5162/12dss2015/P7.2

G. Hagen, N. Leupold, S. Wiegärtner, J. Kita, R. Moos:

Neuartige Sensoranwendung zur Katalysator-Materialcharakterisierung
G. Gerlach, A. Schütze (Hrsg.), *12. Dresdner Sensor-Symposium*, 7.-9. Dezember 2015, Dresden, p. 230-233, doi: 10.5162/12dss2015/P7.5

J. Exner, R. Moos:

Ermittlung spezifischer Materialkennwerte von Schichten mittels Interdigital-Elektroden
G. Gerlach, A. Schütze (Hrsg.), *12. Dresdner Sensor-Symposium*, 7.-9. Dezember 2015, Dresden, p. 256-259, doi: 10.5162/12dss2015/P7.10

J. Kita, S. Wiegärtner, R. Moos, P. Weigand, A. Pliscott, M.H. LaBranche, H.D. Glicksman:

Screen-printable type S thermocouple for thick-film technology
EuroSensors XXIX, September 6 - 9, 2015, Freiburg, Germany, MP-K03
Procedia Engineering, **120**, 828-831 (2015), doi: 10.1016/j.proeng.2015.08.692

A. Brandenburg, E. Wappler, J. Kita, R. Moos:

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EuroSensors XXIX, September 6 - 9, 2015, Freiburg, Germany, BS02-3
Procedia Engineering, **120**, 116-119 (2015), doi: 10.1016/j.proeng.2015.08.579

F. Schubert, S. Wollenhaupt, J. Kita, G. Hagen, R. Moos:

Lessons learned during the development of a manufacturing process for switching-type lambda sensors as a basis for new exhaust gas sensors
90. DKG Jahrestagung / Symposium Hochleistungskeramik 2015, Bayreuth, 15.3.-19.3.2015, p. 167

J. Kita, A. Engelbrecht, F. Schubert, A. Groß, F. Rettig, R. Moos:

Some practical points to consider with respect to thermal conductivity and electrical resistivity of ceramic substrates for high-temperature gas sensors
Sensors and Actuators B: Chemical, **213**, 541-546 (2015), doi: 10.1016/j.snb.2015.01.041

D. Ortolino, A. Engelbrecht, H. Lauterbach, M. Bräu, J. Kita, R. Moos:

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Journal of Ceramic Science and Technology, **5**, 317-326 (2014), doi: 10.4416/JCST2014-00029

J. Kita, A. Brandenburg, I. Sudina, R. Moos:

High-Temperature Miniaturized Furnace manufactured in HTCC-Technology
38th International Microelectronics and Packaging IMAPS Conference, Rzeszów-Czarna, Poland, 21. - 24.09.2014

A. Brandenburg, E. Wappler, R. Moos, J. Kita:

Development and optimization of a novel miniaturized ceramic differential scanning calorimeter
Thermal Analysis and Calorimetry in Industry and Research - 40 Years of GEFTA, Berlin, Germany, September 16 - 19, 2014, p. E2

A. Brandenburg, J. Kita, E. Wappler, R. Moos:

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J. Kita, W. Missal, E. Wappler, F. Bechtold, R. Moos:

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Journal of Ceramic Science and Technology, **4**, 137-144 (2014), doi: 10.4416/JCST2013-00008

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W. Missal, J. Kita, E. Wappler, F. Gora, A. Kipka, T. Bartnitzek, F. Bechtold, D. Schabbel, B. Pawlowski, R. Moos:

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Sensors and Actuators A: Physical, **172**, 21-26 (2011), doi: 10.1016/j.sna.2011.01.025

D. Ortolino, J. Kita, R. Moos, R. Wurm, A. Pletsch, K. Beart:

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D. Ortolino, J. Kita, R. Wurm, E. Blum, K. Beart, R. Moos:

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35th International Microelectronics and Packaging IMAPS Conference, Gdansk, Poland 21. - 24.09.2011, p. 289-292

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Journal of the European Ceramic Society, **29**, 3265–3271 (2009), doi:10.1016/j.jeurceramsoc.2009.05.019

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Sensors and Actuators B: Chemical, **139**, 394-399 (2009), doi: 10.1016/j.snb.2009.03.011

D. Nowak, E. Miś, A. Dziedzic, J. Kita:

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Microelectronics Reliability, **49**, 600-606 (2009), doi: 10.1016/j.microrel.2009.02.019

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Platform for a hydrocarbon exhaust gas sensor utilizing a pumping cell and a conductometric sensor

Sensors, **9**, 7498-7508 (2009), doi:10.3390/s90907498

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In W. Kollenberg (Hrsg.): Technische Keramik, Vulkan-Verlag GmbH, Essen (2009), 605-609, 2. Auflage, ISBN 978-3-8027-2953-9

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Properties and Applications of Zero-Shrinkage LTCC

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